

## COMPLETE LISTING OF THE CLAIMS

The following lists all of the claims that are or were in the above-identified patent application.

1-18. Canceled.

19. (Previously Presented) A method for packaging an integrated circuit die, comprising:

attaching the die to a substrate so that metal bumps on the die contact conductive traces on a face of the substrate;

treating the face of the substrate so that a fill material when liquid has a higher affinity for a first portion of the substrate and a lower affinity for a second portion of the substrate, wherein the first portion surrounds an area where the die attaches to the substrate and the second portion surrounds the first portion; and

dispensing the fill material as a liquid to fill a gap between the die and the substrate, wherein the fill material flows onto the first portion of the substrate, and the higher affinity of the first portion causes the fill material to bead on the first portion of the substrate.

20. (Previously Presented) The method of claim 19, wherein treating the face of the substrate comprises forming a region of a material on the first portion of the substrate.

21. (Previously Presented) The method of claim 20, wherein the material comprises a substance selected from the group consisting of polymers, metals, ceramics, and combination thereof.

22. (Previously Presented) The method of claim 19, wherein treating the face of the substrate comprises roughening the first portion of the substrate.

23. (Previously Presented) The method of claim 19, further comprising curing the fill material to preserve a shape of the fill material including a bead on the first portion.

24. (Previously Presented) The method of claim 19, wherein beading of the liquid fill

material on the first portion of the substrate prevents formation of thin fillet regions of the fill material.

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